IT & Electronics

Field Intelligence Report

Vol. 48 | 2026.06.15 — 06.21 | Articles: 147

Semiconductor Packaging / AI & Machine Learning / Quantum Computing / Photonics & Optical Comms

Market Mood

78

/ 100 Optimistic

AI-Driven Infrastructure & Advanced Computing

Global investments and technological breakthroughs accelerate next-gen AI, quantum, and optical interconnects, shifting bottlenecks and creating new market opportunities.

AI Data Center Market Growth	CoWoS Capacity Expansion	Quantum Computing Investment	Optical Interconnect Speed
25%+	**120K-140K**	**$8.3B**	**1.6T**
$21-49B by 2026	by 2026	in 2025	New Standard

Weekly Summary

The IT & Electronics domain is experiencing rapid transformation, primarily fueled by AI. Advanced semiconductor packaging, including CoWoS and emerging glass substrates, is critical for AI chip performance, with capacity expanding globally. AI & Machine Learning sees multimodal models and autonomous agents driving enterprise adoption, alongside a critical shift to liquid cooling for data centers. Quantum Computing is progressing towards fault-tolerance with significant national investments and PQC migration deadlines looming. Photonics and optical communications are becoming the new bottleneck for AI data centers, driving innovation in CPO and 1.6T modules. Western players must strategically invest in these converging technologies to maintain competitive edge.

4 Sub-Topic Summary

Sub-Topic	Headline	Momentum	Key Insight

Semiconductor Packaging	AI Demand Drives 2026 CoWoS Capacity to 140K Wafers/Month, Shifting Bottlenecks	**Accelerating**	AI demand drives 2026 CoWoS capacity to 120K-140K wafers/month, narrowing the supply gap to 10%. Glass core substrates are emerging as a next-gen solution, with Intel investing over $1 billion for 2026-2030 production. Western OSATs like Amkor are investing $7 billion in US facilities, while materials suppliers like Henkel bolster HBM packaging R&D.; The bottleneck is shifting to hyper-scale packaging and advanced process technology.
AI & Machine Learning	Multimodal AI & Autonomous Agents Drive Enterprise Adoption, Liquid Cooling Becomes Imperative	**Accelerating**	Multimodal AI models like GPT-4o and Gemini 3.5 Flash are setting new standards in 2026, processing diverse data types with emotional awareness. Autonomous AI agents are gaining enterprise adoption for multi-step workflows, with governance and human-in-the-loop controls becoming critical. AI is accelerating drug discovery by 10,000x and improving pharma OEE by 15-45%. Liquid cooling is now imperative for AI data centers, handling 100kW+ rack densities and driving a $21-49 billion market by 2026.
Quantum Computing	Fault-Tolerant Quantum Progress Accelerates, PQC Migration Deadlines Loom by 2030	**Building**	Microsoft and Quantinuum achieved an 800-fold reduction in logical qubit error rates, with Microsoft targeting a commercial quantum computer by 2029. US government committed over $2 billion in quantum investment, including $1 billion for IBM's quantum chip foundry. PQC migration deadlines loom by 2030, with NIST standards finalized. Atom Computing secured $300M+ and a $100M CHIPS Act LOI to scale neutral atom systems, while D-Wave demonstrated million-fold computational advantage in materials discovery.

Photonics & Optical Comms	Optical Interconnects Become New AI Bottleneck, Driving CPO & 1.6T Module Innovation	**Accelerating**	AI data center bottlenecks are shifting from GPUs to optical interconnects, driving demand for 1.6T modules and Co-Packaged Optics (CPO). Tower Semiconductor and Marvell shipped over 5 million coherent PICs, while Coherent breaks ground on a Texas InP fab with $2 billion NVIDIA backing. Goldman Sachs and Barclays identify optical communications as the next major wave of AI infrastructure investment, with silicon photonics becoming the backbone for HPC and AI data centers.

□□ JAPAN EXCLUSIVE

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IT & Electronics — Weekly Intelligence from Japan

2026.06.15 — 06.21 | Sources: TDnet, METI, NEDO, Gemini Search Grounding

Kioxia Reports Explosive Q1 Growth, Projects Strong Q2 Amid Memory Market Surge

Source: PR Times Report

Summary: Kioxia announced a significant financial turnaround, with Q1 2026 revenue surging 189% year-over-year to 1,029 billion JPY and operating profit increasing 15-fold to 596.8 billion JPY. The company forecasts even stronger Q2 2026 results, projecting revenue of ...

WHY ENGINEERS SHOULD CARE

Procurement teams should re-evaluate NAND flash and DDR5 pricing trends, anticipating continued upward pressure on costs and potential supply tightness for high-capacity modules. Design engineers shou...

Rapidus Accelerates 2nm/1nm Roadmap, Targets 2027 Mass Production

Source: Gemini Grounding (Tokyo Electron section, citing industry developments)

Summary: Rapidus Corporation is aggressively advancing its logic semiconductor roadmap, targeting pilot production for 2nm chips and aiming for mass production by 2027. The company plans to begin 1.4nm process development in 2026 and achieve 1nm mass production by 2029...

WHY ENGINEERS SHOULD CARE

Technical planners and design teams should monitor Rapidus's progress on 2nm and 1nm process nodes for potential new foundry options in advanced logic. Evaluate their PDK maturity and IP ecosystem as ...

Japan Commits Over 50 Trillion JPY to Semiconductor & AI by FY2030

Source: NEDO, METI (MirasapoPlus, Government Growth Strategy Draft)

Summary: The Japanese government, through METI and NEDO, is committing to a massive public-private investment of over 50 trillion JPY (approximately $320 billion USD) in the semiconductor and AI sectors by fiscal year 2030. This initiative, part of the "AI/Semiconducto...

WHY ENGINEERS SHOULD CARE

Strategic planners and procurement leads should recognize Japan's long-term commitment to bolstering its domestic semiconductor and AI ecosystem. This indicates potential for stable supply chains, new...

This Week's Japan Technology Highlights

Japan's IT sector sees Kioxia's Q1 revenue jump 189% YoY amid a memory market surge (DDR5 16G >$40), while Rapidus targets 2nm mass production by 2027.

□□ CHINA WATCH

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IT & Electronics — Technical Verification (Western Engineer Perspective)

2026.06.15 — 06.21 | 3-Axis: China Move / Verification / Engineer Implications

SMIC's 7nm (N+3) Process and Huawei's Kirin 9030: Yield Challenges Persist

■ China's Move

SMIC is actively producing its third-generation 7nm (N+3) process, which is being utilized in Huawei's Kirin 9030 chip for the Mate 80 series (reuters.com, ft.com, techcrunch.com, tomshardware.com). The N+3 process reportedly achieved a transistor density of 1...

■ Technical Verification

[CONFIRMED]	SMIC is producing its N+3 process, used in Huawei's Kirin 9030. / The Kirin 9030 chip is featured in the Huawei Mate 80 series.
[BOTTLENECK]	Achieving high, economically viable yields for advanced nodes (N+3) without EUV lithography. / Mastering Gate-All-Around (GAA) transistor technology for volume production.

■ Implications for Western Engineers

- Mobile SoC Design Teams: Benchmark Kirin 9030 performance against 2021-2022 era Western mobile SoCs, not current flagships, for ...
- Process Technology Engineers: Analyze SMIC's N+3 density claims with skepticism; focus on independent verification of actual dev...
- Procurement Professionals: Factor in potentially higher cost-per-die and lower availability for advanced Chinese-made chips due ...

CXMT's DDR5/LPDDR5X Memory Expansion: Performance & Supply Chain Implications

■ China's Move

ChangXin Memory Technologies (CXMT) is expanding its DDR5 production and manufacturing capacity (reuters.com, ft.com, techcrunch.com, tomshardware.com). CXMT's CXDD7JEDM (G4 process) memory component, comparable to other 1z processes, is included in the Huawei...

■ Technical Verification

[CONFIRMED]	CXMT is producing DDR5 and LPDDR5X memory chips on its 16nm (G4) node. / CXMT's CXDD7JEDM memory component is integrated into the Huawei Mate 80 Pro Max.
[BOTTLENECK]	Achieving competitive performance (bandwidth, latency) and power efficiency with DUV-only processes compared to EUV-enabled advanced DRAM nodes. / Scaling production of high-density, high-speed serv...

■ Implications for Western Engineers

- Memory Design & Validation Teams: Independently benchmark CXMT's DDR5/LPDDR5X for bandwidth, latency, and power efficiency again...
- System Architects: Evaluate CXMT memory for specific applications where cost-effectiveness or supply chain diversification outwe...
- Procurement Professionals: Assess the risk/benefit of incorporating CXMT memory, considering potential future export control imp...

Key Trends This Week (5 Total)

TR-01 HIGH Cross-Domain

AI-Driven Infrastructure Demand Surges, Reshaping Supply Chains

AI Workloads Drive 2026 CoWoS Capacity to 140K Wafers/Month, Shifting Bottlenecks

The explosive growth of AI workloads is the primary driver across all sub-topics, creating unprecedented demand for advanced semiconductor packaging (CoWoS, HBM), high-speed optical interconnects (1.6T, CPO), and specialized cooling solutions (liquid cooling for 100kW+ racks). This demand is shifting infrastructure bottlenecks from GPUs to packaging and optical layers, necessitating massive investments and capacity expansions globally.

CoWoS Capacity by 2026	AI Data Center Market by 2026	NVIDIA Coherent PIC Investment
120K-140K wafers/month	$21-49 Billion	$2 Billion

▶ Western OEM ▶ Western Contract Manufacturer ▶ Western Equipment Maker ▶ Western Material Supplier

Refs: S1-04 S1-05 S1-18 S1-23 S2-12 S2-13 S2-21 S2-28 S4-02 S4-06 S4-07 S4-13 S4-18

TR-02 HIGH Cross-Domain

Geopolitical Competition & Sovereign Tech Investment Intensify

US Commits $2B to Quantum, EU AI Act Accelerates, Driving Domestic Supply Chains

Governments worldwide, particularly the US and EU, are making significant strategic investments to secure technological sovereignty in critical areas like quantum computing and advanced semiconductors. The US CHIPS Act is directing over $2 billion into quantum, including a $1 billion IBM quantum chip foundry, and supporting advanced packaging in Arizona. The EU AI Act is rapidly establishing regulatory frameworks, while partnerships like US-Japan and UK-Japan focus on commercial quantum deployment, signaling a shift from research grants to industrialization.

US Quantum Investment	IBM Quantum Foundry Investment	EU AI Act High-Risk Deadlines
$2.013 Billion	$1 Billion	Dec 2027 / Aug 2028

▶ Western OEM ▶ Western Contract Manufacturer ▶ Western Equipment Maker ▶ Western Material Supplier

Refs: S1-14 S1-28 S1-30 S2-18 S2-23 S3-06 S3-13 S3-18 S3-26 S3-27 S3-29 S3-31 S3-41 S3-52

TR-03 MED Semiconductor Packaging, Photonics & Optical Comms

Next-Gen Packaging & Optical Interconnects Overcome Physical Limits

Glass Substrates & CPO Emerge to Break AI Performance Bottlenecks by 2028

To sustain AI's exponential growth, the industry is rapidly adopting and developing next-generation packaging and optical interconnect technologies. Glass core substrates are gaining traction for advanced packaging, with Intel investing over $1 billion for high-volume production by 2030, offering superior thermal and electrical properties. Co-Packaged Optics (CPO) and Near-Package Optics (NPO) are becoming essential for AI data centers to overcome copper's limitations, enabling 1.6T speeds and picojoule-class power efficiency.

Intel Glass Substrate Investment	TSMC CoPoS Mass Production Target	Optical Module Speed
$1 Billion+	**Late 2028**	**1.6T**

▶ Western OEM ▶ Western Contract Manufacturer ▶ Western Material Supplier ▶ Western Equipment Maker

Refs: S1-02 S1-06 S1-07 S1-09 S1-12 S1-19 S1-34 S4-03 S4-04 S4-05 S4-06 S4-08 S4-11 S4-13 S4-16 S4-23

TR-04 MED AI & Machine Learning

AI Agents & Multimodal Models Drive Enterprise Automation & Governance

Multimodal AI Becomes Standard, Autonomous Agents Automate Workflows with Governance Focus

Multimodal AI, exemplified by OpenAI GPT-4o and Google Gemini 3.5 Flash, is now a standard for frontier models, enabling real-time processing of diverse data types with emotional awareness. Autonomous AI agents are increasingly adopted by enterprises to execute complex, multi-step workflows, driving significant OEE improvements (15-45% in pharma). This shift necessitates robust governance frameworks, human-in-the-loop controls, and focus on data security to mitigate risks and ensure responsible deployment.

Pharma OEE Improvement	Antibiotic Efficacy Boost	LLM Clinical Score Gap
15-45%	**68%**	**92% vs 44.8%**

▶ Western OEM ▶ Western T&M; Provider ▶ Western Distributor

Refs: S2-02 S2-04 S2-05 S2-08 S2-09 S2-16 S2-19 S2-20 S2-23 S2-25 S2-26 S2-30 S2-31

TR-05 LOW Quantum Computing

Quantum Computing Progresses Towards Fault-Tolerance & PQC Migration

Quantum Error Correction Achieves 800x Fidelity, PQC Migration Deadlines Set for 2030

Significant strides are being made towards fault-tolerant quantum computing, with Microsoft and Quantinuum demonstrating an 800-fold reduction in logical qubit error rates and Microsoft targeting a commercial quantum computer by 2029. D-Wave showcased million-fold computational advantage in materials discovery. Concurrently, the urgent need for Post-Quantum Cryptography (PQC) migration is highlighted, with NIST standards finalized and SMBs facing a 2030 deadline, posing infrastructure challenges due to larger key sizes.

Logical Error Rate Reduction	Qubit Reliability Improvement	PQC Migration Deadline
800-fold	**1000x**	**2030**

▶ Western OEM ▶ Western T&M; Provider ▶ Western Equipment Maker

Refs: S3-03 S3-04 S3-05 S3-07 S3-08 S3-09 S3-10 S3-11 S3-15 S3-17 S3-21 S3-22 S3-23 S3-30 S3-37 S3-38 S3-39 S3-40 S3-42 S3-43 S3-44 S3-46 S3-47 S3-49 S3-50 S3-53 S3-54

Macro Market Indicators

Indicator	Direction	Value	Note	Source
US CHIPS Act Quantum Funding	↑	$2.013 Billion	Total US Department of Commerce investment in quantum technology, including $1B for IBM's quantum chip foundry.	SRI International (S3-41)
EU AI Act Implementation	↑	Accelerating	Poland passes AI Systems Act; Ireland to establish National AI Office by August 2, 2026.	EU Artificial Intelligence Act (S2-18)
Global Quantum VC Funding	↑	$8.3 Billion	Global venture capital deals in quantum technology in 2025, with 48.2% of post-2025 deals in last 18 months.	Preqin (S3-06)
US AI Data Center Power Demand	↑	123 GW	Projected power requirement for US AI data centers by 2035.	Digital Applied (S2-13)

Macro Environment Summary

Global technology policy and investment are accelerating, with the US CHIPS Act injecting over $2 billion into quantum and advanced packaging, while the EU AI Act establishes regulatory frameworks by Q3 2026. Venture capital in quantum computing surged to $8.3 billion in 2025, with nearly half of post-2025 deals occurring in the last 18 months. This rapid expansion, particularly in AI, is driving unprecedented power demand, with US AI data centers projected to require 123 GW by 2035, necessitating new cooling and energy strategies.

Market Data: SOXX (Semiconductors) Weekly Trend

639.45 USD +7.30%

TSMC CoWoS Capacity & Gap 20% (early 2026) → 10% (end 2026): Halved

Capacity projected to reach 120K-140K wafers/month by end-2026, still tight with NVIDIA reserving 60%.

Action Recommendations by Player

Action Recommendations for Western OEM

OEM NVIDIA, AMD, Intel, Sanofi, Arista Networks, Ciena, Microsoft, Google, HPE

NVIDIA maintains 80% AI chip market dominance via CUDA, while AMD's MI350 GPUs show 3.5x generational gains. Intel invests over $1B in glass substrate R&D; for 2026-2030 production. Sanofi aims to be the 'first AI-powered biopharma at scale,' integrating AI across its value chain.

Risk

- If CoWoS/CPO supply remains tight, product launch delays for AI systems will exceed 12 months
- If PQC migration is not planned by 2027, critical data security will be compromised by 2030
- If liquid cooling is not adopted, AI data center power costs will increase 15-20% by 2027

Opportunity

- Integrate multimodal AI agents for 15-45% OEE improvement in manufacturing, targeting $5B+ market by 2028
- Invest in next-gen optical interconnects (CPO/NPO) to secure 1.6T+ bandwidth for AI clusters, addressing $1T+ market
- Partner with quantum computing firms for early access to fault-tolerant systems, gaining 2-3 year lead in drug discovery

Actions This Week

- Establish a cross-functional AI/Quantum/Packaging task force by end of this week to assess supply chain risks
- Initiate R&D; partnerships with glass substrate and CPO suppliers within 3 months to secure future component access
- Develop a PQC migration roadmap by Q3 2026, prioritizing high-risk data and systems for 2030 compliance

☐ Scenario: If AI demand continues to outstrip advanced packaging and optical interconnect supply through 2027, Western OEMs without diversified sourcing and in-house capabilities will face 18-24 month product delays and significant market share loss — begin dual-sourcing and strategic IP acquisition now.

☐ Quick Win : Schedule immediate meetings with TSMC, Amkor, and Coherent to secure 2027 CoWoS/CPO capacity allocations and explore joint development for glass substrates.

Action Recommendations for Western Contract Manufacturer

Foundry Amkor, GlobalFoundries, Lonza

Amkor is investing $7 billion in its Arizona facility to establish the first high-volume advanced OSAT in the US, securing a 10-year deal with TSMC. GlobalFoundries received $375 million from the US government under the CHIPS Act, transferring a minority equity stake.

Risk

- If Asian competitors outpace Western OSATs in CoPoS/glass substrate mass production, market share will decline by 10-15% by 2029
- If labor shortages in key regions like Vietnam persist, advanced packaging capacity expansion will be delayed by 6-12 months
- If capital expenditure for next-gen packaging exceeds ROI, financial stability will be impacted by 2028

Opportunity

- Secure long-term contracts for CoWoS/CoPoS with Western AI chip designers, targeting $3.5B+ revenue by 2026 (ASE example)
- Develop expertise in glass core substrates and TGV formation, positioning for $1B+ market by 2030

- Expand US/EU advanced packaging capacity, leveraging government incentives to build resilient domestic supply chains

Actions This Week

- Accelerate Arizona fab construction to meet 2027 CoWoS demand, leveraging CHIPS Act funding within 6 months
- Invest in R&D; for glass substrate processing and TGV technology by Q4 2026, targeting pilot production by 2028
- Diversify advanced packaging offerings beyond HBM to include chiplet and 3D integration for HPC by Q1 2027

☐ Scenario: If the US government's CHIPS Act funding for advanced packaging does not translate into sustained demand from Western OEMs by 2028, then Western OSATs risk underutilized capacity and financial strain — actively engage with top-tier AI chip designers to co-invest in future capacity now.

☐ Quick Win : Finalize 2027 capacity reservation agreements with top 3 Western AI chip designers for CoWoS and HBM packaging by end of this month.

Action Recommendations for Western T&M; Provider

T&M; Keysight, Park Systems, Teradyne, NI

Keysight expanded its Photonic Design Automation portfolio with system-level simulation for optical communications. Park Systems partnered with imec for next-gen 3D packaging and logic metrology, accelerating vital inspection technologies.

Risk

- If metrology solutions for glass substrates and CPO are not developed by 2027, market entry for next-gen packaging will be delayed
- If quantum computing error rates remain high, demand for quantum test equipment will be limited until 2029
- If AI-driven design automation tools are not integrated, competitive advantage will erode by 2028

Opportunity

- Develop metrology tools for glass core substrates and CoPoS, addressing a $500M+ market by 2029
- Offer PQC migration assessment and validation services for enterprises, targeting $1B+ cybersecurity market by 2030
- Partner with quantum hardware developers to co-design test solutions for fault-tolerant systems, securing early market leadership

Actions This Week

- Launch a dedicated R&D; initiative for glass substrate and CPO metrology by Q3 2026, targeting early adopter customers
- Develop quantum error correction validation tools within 12 months, collaborating with IBM and Quantinuum
- Integrate AI/ML into existing test platforms by Q4 2026 to enhance predictive maintenance and yield optimization

☐ Scenario: If the transition to glass substrates and Co-Packaged Optics accelerates faster than current metrology capabilities, Western T&M; providers will lose critical market share to agile competitors — prioritize R&D; for these specific technologies and engage with leading foundries by Q4 2026.

☐ Quick Win : Host a 'Glass Substrate Metrology Challenge' with imec and Intel by next month to identify key R&D; gaps and potential solutions.

Action Recommendations for Western Material Supplier

Material Henkel, BASF, Dow, DuPont, Umicore

Henkel is expanding electronics materials investment in South Korea, bolstering HBM packaging material development for AI semiconductors. ABF substrates are a critical bottleneck for AI accelerators, driving demand for next-gen solutions like glass.

Risk

- If glass substrate material challenges (brittleness, TGV formation) are not resolved by 2028, market adoption will be delayed
- If Asian competitors dominate advanced packaging material innovation, Western suppliers will lose market share by 15-20% by 2029
- If environmental regulations tighten on current packaging materials, R&D; costs for compliant alternatives will increase by 10-20%

Opportunity

- Develop advanced materials for glass core substrates (e.g., low-CTE glass, TGV fill materials), targeting $1B+ market by 2030
- Innovate in thermal interface materials (TIMs) and encapsulants for liquid-cooled AI systems, addressing $500M+ market by 2028
- Supply specialized materials for quantum computing components (e.g., cryogenic materials, topological qubit substrates), securing early market entry

Actions This Week

- Form a joint development program with Intel and TSMC on glass substrate materials by Q3 2026, focusing on brittleness and TGV
- Increase R&D; investment in advanced thermal management materials for AI data centers by 20% within 6 months
- Evaluate strategic acquisitions of smaller, innovative material startups in advanced packaging or quantum by Q1 2027

☐ Scenario: If current ABF substrate limitations for AI accelerators are not overcome by 2027 through new material innovations, Western material suppliers will face significant revenue stagnation as the industry shifts to alternative solutions — accelerate R&D; into next-gen substrate materials and engage with leading AI chip designers now.

☐ Quick Win : Initiate a technical review with Henkel and DuPont R&D; teams this week to identify immediate opportunities in HBM4E and glass substrate materials.

Action Recommendations for Western Distributor

Distributor Arrow, Avnet, Brenntag

No specific Western distributors mentioned, but the role is critical in managing complex supply chains for advanced components like HBM, optical modules, and PQC-ready hardware.

Risk

- If supply chain visibility for advanced packaging and optical components remains low, inventory holding costs will increase by 10-15%
- If PQC-ready hardware is not readily available, customer migration will be delayed, impacting sales by 2030
- If geopolitical tensions disrupt key manufacturing hubs, component sourcing will face 6-12 month delays

Opportunity

- Offer value-added services for PQC migration (e.g., inventory, integration support), targeting $500M+ market by 2030
- Become a preferred supplier for liquid cooling components and AI data center infrastructure, addressing $21-49B market

- Develop specialized logistics for quantum computing hardware, securing niche market leadership by 2029

Actions This Week

- Establish a dedicated PQC-ready product catalog and supply chain by Q4 2026, including training for sales teams
- Partner with leading liquid cooling solution providers within 3 months to offer integrated AI data center packages
- Implement advanced AI-driven supply chain analytics by Q1 2027 to improve visibility and mitigate geopolitical risks

☐ Scenario: If the complexity of AI-driven supply chains for advanced packaging and optical interconnects overwhelms traditional distribution models, Western distributors will lose market share to specialized logistics providers — invest in AI-powered supply chain optimization and strategic partnerships with niche component makers by Q3 2026.

☐ Quick Win : Conduct a comprehensive audit of current AI/HPC component inventory and identify PQC-ready alternatives by end of this week.

Action Recommendations for Western Equipment Maker

Equipment Lam Research, Applied Materials, Thermo Fisher, Sartorius, HPE

Lam Research forecasts over 50% growth in advanced packaging revenue by 2026, solidifying its role as a key AI 'picks and shovels' provider. HPE is expanding partnerships for hybrid quantum supercomputing, integrating classical and quantum hardware.

Risk

- If equipment for glass substrate processing and CoPoS is not ready by 2027, market entry for next-gen packaging will be missed
- If quantum computing hardware development slows, demand for specialized manufacturing equipment will be limited until 2029
- If Asian competitors dominate advanced packaging equipment, Western market share will decline by 10-15% by 2028

Opportunity

- Develop and supply equipment for glass core substrate manufacturing (TGV, bonding), targeting $1B+ market by 2030
- Provide advanced liquid cooling systems for 100kW+ AI data center racks, addressing $5B+ market by 2028
- Partner with quantum foundries (e.g., IBM) to develop specialized fabrication tools for quantum chips, securing early market leadership

Actions This Week

- Accelerate R&D; for glass substrate processing equipment by Q3 2026, targeting Intel and TSMC as early customers
- Develop modular, scalable liquid cooling solutions for multi-megawatt AI data centers within 9 months
- Engage with IBM and Quantinuum by Q4 2026 to co-develop next-gen quantum chip manufacturing tools

☐ Scenario: If the shift to glass substrates and Co-Packaged Optics requires entirely new manufacturing equipment, Western equipment makers without proactive R&D; will face significant obsolescence risk — initiate joint development programs with leading foundries and material suppliers for these technologies by Q3 2026.

☐ Quick Win : Host a technical workshop with Intel's Arizona glass R&D; team by next month to align on equipment requirements for 2027 pilot production.

Impact Matrix (Players × Trends)

++ = Strong Tailwind + = Tailwind 0 = Neutral – = Headwind –– = Strong Headwind

Player	TR-01 HIGH AI-Dri	TR-02 HIGH Geopol	TR-03 MED Next-G	TR-04 MED AI Age	TR-05 LOW Quantu
Western OEM	++	+	++	++	+
Western Contract Manufacturer	++	++	++	0	0
Western T&M; Provider	+	+	+	+	++
Western Material Supplier	+	+	++	0	+
Western Distributor	+	+	+	+	+
Western Equipment Maker	++	+	++	0	+

Timeline This Week (10 Events)

Date	Tag	Headline	Source
2026-06-11	milestone	Lam Research forecasts >50% advanced packaging revenue growth by 2026	USA S1-23
2026-06-12	milestone	Microsoft & Quantinuum achieve 800-fold logical error rate reduction	USA S3-05
2026-06-12	deal	US & Japan forge $1B strategic partnership in Quantum & AI	USA, Japan S3-31
2026-06-15	milestone	TSMC narrows CoWoS supply gap to 10% by end-2026	Taiwan S1-04, S1-18
2026-06-16	deal	Coherent breaks ground on Texas InP fab with $2B NVIDIA backing	USA S4-02
2026-06-17	deal	Atom Computing secures $300M+ funding, including $100M CHIPS Act LOI	USA S3-18
2026-06-18	product	SK Hynix begins shipping 12-layer HBM4E samples	South Korea S1-24, S1-33
2026-06-19	policy	EU AI Act high-risk rules deadlines extended to Dec 2027 / Aug 2028	Europe S2-23
2028	milestone	QuEra targets launch of 'Libra' fault-tolerant quantum computer on Amazon Braket	USA S3-03, S3-45
2029	milestone	Microsoft targets commercial quantum computer launch	USA S3-10, S3-46

Company Spotlight

Amkor Technology [AMKR] ↑ Strategic US Expansion

Amkor is investing $7B in its Arizona facility, acquiring 67 acres to build the first high-volume advanced OSAT in the US, securing a 10-year deal with TSMC for CoWoS and InFO packaging. This solidifies its role in the domestic semiconductor ecosystem.

- Accelerate Arizona fab construction to meet 2027 CoWoS demand, leveraging CHIPS Act funding within 6 months
- Engage with US government agencies to secure further incentives for domestic advanced packaging capacity
- Diversify advanced packaging offerings beyond HBM to include chiplet and 3D integration for HPC by Q1 2027

Quantinuum ↑ Quantum Error Correction Breakthrough

In partnership with Microsoft, Quantinuum achieved an 800-fold reduction in logical qubit error rates on its H2 processor, demonstrating 14,000 consecutive error-free operations. Their 98-qubit Helios processor also achieved 99.921% two-qubit gate fidelity, accelerating fault-tolerant quantum computing.

- Expand collaborations with leading research institutions (e.g., PNNL) to benchmark fault-tolerant systems by Q4 2026
- Accelerate development of commercial applications leveraging improved qubit fidelity, targeting early adopters in chemistry/materials science within 12 months
- Secure additional strategic partnerships for hybrid quantum-classical supercomputing platforms by Q1 2027

Ciena [CIEN] ↑ AI-Driven Revenue Surge

Ciena reported significantly increased AI-driven revenue and raised full-year guidance, solidifying its leadership in AI optical networking. Its solutions are critical for resolving bandwidth and latency bottlenecks in AI data centers, enabling 1.6T+ interconnects.

- Increase R&D; investment in Co-Packaged Optics (CPO) and 1.6T optical modules by 15% within 6 months to maintain market leadership
- Expand sales and engineering teams focused on AI data center infrastructure solutions by Q3 2026
- Form strategic alliances with major AI chip designers and hyperscalers to co-develop next-gen optical interconnect standards by Q4 2026

Technology Roadmap

2026

- ◆ TSMC CoWoS capacity reaches 120K-140K wafers/month
- ◆ Lam Research advanced packaging revenue grows >50%
- ◆ Multimodal AI becomes frontier model standard

2027

- ◆ EU AI Act high-risk standalone systems compliance deadline (Dec)
- ◆ NVIDIA's Feynman platform adopts CoPoS pilot production
- ◆ Intel targets glass substrate high-volume production

2028

- ◆ QuEra launches 'Libra' fault-tolerant quantum computer on Amazon Braket
- ◆ NVIDIA's Feynman platform adopts CoPoS mass production

- ◆ EU AI Act high-risk integrated products compliance deadline (Aug)

2029

- ◆ Microsoft targets commercial quantum computer launch with Majorana 2 chip
- ◆ AI data center market projected to reach $620B

2030

- ◆ Intel targets high-volume glass core substrate production
- ◆ SMBs face urgent PQC migration deadline
- ◆ Fujitsu & RIKEN target 10,000+ physical qubits

References (147 Total)

ID	Title	Source	Date	Region	Sub-Topic
S1-01	Samsung, SK Hynix Eye Honam Region in South Korea for First Advanced Packaging Fabs Amid Soaring AI Memory Demand; Amkor Plans $980M Expansion	The Elec Inc.	2026-06-14	South Korea	Semiconductor Packaging
S1-02	Advanced Packaging: Glass Core Substrates Emerge as Next-Gen Frontier; Intel Commits Over $1 Billion to R&D; for High-Volume Production by 2030	Infra Startups	2026-06-13	US	Semiconductor Packaging
S1-03	AT&S; Unveils €2 Billion Kulim Expansion to Fuel AI Boom with Advanced IC Substrates and PCBs	AT&S; Official Press Release	2026-06-15	Austria	Semiconductor Packaging
S1-04	TSMC Narrows CoWoS Supply-Demand Gap from 20% to 10% by End of 2026; NVIDIA to Adopt Next-Gen CoPoS for 2028-2029 Mass Production	Moomoo	2026-06-15	Singapore	Semiconductor Packaging
S1-05	TSMC's CoWoS Capacity, Targeting 125K-130K Wafers/Month by 2026, Still Falls Short as Nvidia Reserves 60% of Output	INDmoney	2026-06-17	India	Semiconductor Packaging
S1-06	ABF Substrates Become AI Accelerator Bottleneck, Nvidia's H100 Requires 12+ Layers; Glass Substrates Emerge as Next-Gen Solution, Commercialization Years Away	Data Gravity	2026-06-14	US	Semiconductor Packaging
S1-07	TSMC Strengthens Glass Substrate Supply Chain for CoWoS, Achieving 16% Warpage Reduction for High-Performance AI GPUs	Wccftech	2026-06-16	US	Semiconductor Packaging
S1-08	Henkel Expands Electronics Materials Investment in Korea, Bolstering HBM Packaging Material Development for Surging AI Semiconductor Demand	The Elec Inc.	2026-06-17	South Korea	Semiconductor Packaging
S1-09	Glass Core Substrates Emerge as Next-Gen AI/HPC Packaging Technology, Face Commercialization Hurdles in Brittleness and TGV Formation	Pandaily	2026-06-14	China	Semiconductor Packaging
S1-10	ASE Technology Raises 2026 LEAP Revenue Outlook Above $3.5 Billion, Driven by Soaring AI Advanced Packaging Demand	Zacks	2026-06-12	US	Semiconductor Packaging
S1-11	Park Systems and imec Forge Alliance for Next-Gen 3D Packaging and Logic Metrology	imec Official Press Release	2026-06-15	Belgium	Semiconductor Packaging
S1-12	TSMC's CoWoS Shortage Eases, But Bottleneck Shifts to 'Hyper-Scale Packaging' as Google Reportedly Engages Samsung for TPU Production	Zhitong Finance APP	2026-06-15	Hong Kong	Semiconductor Packaging

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S1-13	imec Unleashes High-Density MIMCAP RF Interposer for D-Band Millimeter-Wave and Sub-THz Communications, Accelerating III-V Chiplet Integration	imec	2026-06-15	Belgium	Semiconductor Packaging
S1-14	TSMC and Amkor Sign 10-Year Advanced Packaging Deal in Arizona, Amkor to Invest $7B for CoWoS Supply Boost and US Ecosystem Build-out	Bignewsnetwork	2026-06-16	India	Semiconductor Packaging
S1-15	AI Infrastructure Demand Intensifies Memory Shortage: TSMC CoWoS Constraints and Vietnam Labor Shortages Create Compound Challenges	Sourceability	2026-06-15	US	Semiconductor Packaging
S1-16	Nokia Ramps Up U.S. Advanced Chip Packaging Capacity Tenfold in Pennsylvania to Fuel AI Networks	Cyprus Shipping News	2026-06-19	キプロス	Semiconductor Packaging
S1-17	Malaysia Commits RM185M to Advanced Packaging Consortium, Targeting High-Value AI and HPC Semiconductors	不明	2026-06-15	Malaysia	Semiconductor Packaging
S1-18	TSMC to Halve AI Chip Supply Gap from 20% to 10% by End-2026 with CoWoS Capacity Boost; Next-Gen CoPoS on Track	TrendForce	2026-06-15	Taiwan	Semiconductor Packaging
S1-19	Semiconductor Engineering June 2026 Report Highlights On-Chip Photonics, Hybrid Bonding, and GaN for AI/HPC	Semiconductor Engineering	2026-06-18	US	Semiconductor Packaging
S1-20	AT&S; Commits €2 Billion to Malaysian Expansion, Supercharging AI IC Substrate Capacity for AMD and Key Tech Partners	EQS News	2026-06-15	Austria	Semiconductor Packaging
S1-21	KAIST Develops Breakthrough Liquid Cooling Technology to Shatter AI Semiconductor Thermal Bottleneck	Mirage News	2026-06-16	South Korea	Semiconductor Packaging
S1-22	Samsung's Advanced Packaging Lag Clouds AI Chip Comeback, Falling Behind TSMC and Intel	digitimes	2026-06-12	Taiwan	Semiconductor Packaging
S1-23	Lam Research Forecasts Over 50% Growth in Advanced Packaging Revenue by 2026, Emerging as a Key AI "Picks and Shovels" Provider	XTB.com	2026-06-11	US	Semiconductor Packaging
S1-24	SK Hynix Begins Shipping 12-Layer Next-Gen 'HBM4E' Samples for AI, Delivering Significant Performance and Power Efficiency Gains Amidst NVIDIA CEO's Endorsement	SK hynix Inc.	2026-06-18	South Korea	Semiconductor Packaging
S1-25	SK Hynix Holds U.S. Talks on HBM Supply and Investment Plans, Bolstering Domestic Semiconductor Supply Chain	digitimes	2026-06-19	Taiwan	Semiconductor Packaging

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S1-26	Micron's HBM Capacity Sold Out Through 2026, Securing Position in NVIDIA's Next-Gen AI Platform "Vera Rubin"	Investing.com	2026-06-15	US	Semiconductor Packaging
S1-27	Kaynes Technology Partners with Japan's AOI Electronics to Build ₹3,307 Cr OSAT Plant in India, Boosting Semiconductor Back-End Capabilities	Sahi	2026-06-16	India	Semiconductor Packaging
S1-28	TSMC and Amkor Forge 10-Year Strategic Partnership to Boost U.S. Advanced Packaging Capabilities	Focus Taiwan	2026-06-18	Taiwan	Semiconductor Packaging
S1-29	AT&S; Commits €2 Billion to Accelerate AI/HPC Chip Substrate Production in Asia, Bolstered by AMD Partnership	TNW	2026-06-15	Austria	Semiconductor Packaging
S1-30	Amkor Supercharges U.S. Chip Packaging with 67-Acre Arizona Expansion, Aiming for First High-Volume Advanced OSAT	StocksToTrade	2026-06-16	US	Semiconductor Packaging
S1-31	Intel Appoints Former SK hynix CEO Lee Seok-hee as Senior VP of Advanced Packaging to Bolster AI Systems	The Korea Herald	2026-06-19	South Korea	Semiconductor Packaging
S1-32	Samsung Considers New HBM-Focused Advanced Semiconductor Packaging Plant in South Korea's Honam Region to Meet AI Server Demand	SamMobile	2026-06-14	South Korea	Semiconductor Packaging
S1-33	SK hynix Begins Shipping Next-Gen HBM4E AI Memory Chips with 12-Layer Stack, 48GB Capacity, 16Gbps per Pin, and Over 20% Power Efficiency Boost	Bisinfotech	2026-06-18	South Korea	Semiconductor Packaging
S1-34	TSMC Accelerates CoPoS Packaging Development, Standardizing 310x310mm Panel Format; Introduces Glass Core Substrate for CoWoS Towards Late 2028 Mass Production	TrendForce	2026-06-17	Taiwan	Semiconductor Packaging
S1-35	Nokia Announces Major Expansion of U.S. Advanced Semiconductor Test and Packaging Operations in Pennsylvania, Doubling Workforce to Over 500, to Bolster AI Infrastructure	GlobeNewswire	2026-06-16	US	Semiconductor Packaging
S1-36	Amkor Technology Shifts SiP Production to Vietnam to Enhance High-Value Programs, Driven by Strong Demand for Advanced Packaging in Premium Smartphones	TradingView	2026-06-17	US	Semiconductor Packaging
S1-37	imec Breaks New Ground: III-V Chiplets on RF Silicon Interposer Achieve 100x Capacitance Density Boost and Sub-600nm Precision	OriginBrief	2026-06-15	Belgium	Semiconductor Packaging
S2-01	AI Accelerates Molecular Simulations by Over 10,000x for Rapid Drug Discovery	News-Medical.Net	2026-06-12	International	AI & Machine Learning

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S2-02	AI Robotics in Pharma Manufacturing Drives 15-45% OEE Improvement, Eliminates Defects, and Delivers Rapid ROI	IntuitionLabs	2026-06-14	US	AI & Machine Learning
S2-03	AI Startup Funding Surges: Sarvam AI Secures $234M, TensorWave $350M Amidst US-Focused Investment Boom	Scouts by Yutori	2026-06-15	Japan	AI & Machine Learning
S2-04	Christ Church-Led Team Develops 'PhenoSeq' AI to Accelerate Cancer Drug Discovery by Extracting Transcriptomic Profiles from Cell Images	Christ Church	2026-06-18	UK	AI & Machine Learning
S2-05	AI Agents Automate Enterprise Workflows: Governance and Control Key to Success and Risk Mitigation	Truefoundry	2026-06-12	US	AI & Machine Learning
S2-06	Tensordyne's Napier AI Inference System, Taped Out on TSMC 3nm, Achieves 17x More Tokens/Watt and 13x Higher Throughput than NVIDIA Blackwell	Tensordyne	2026-06-15	US	AI & Machine Learning
S2-07	AMD Instinct MI350 Series GPUs Achieve 3.5x Generational Gain on Llama 2-70B and Competitive LLM Training Performance Against NVIDIA B200 in MLPerf Training 6.0	AMD	2026-06-16	US	AI & Machine Learning
S2-08	Multimodal AI Race Intensifies: Google Gemini 3.5 Flash, OpenAI GPT-5 Lead 6 Frontier Models in 2026 Innovation	Enlight Lab	2026-06-19	US	AI & Machine Learning
S2-09	Autonomous AI Agents Execute Enterprise Workflows, Human-in-the-Loop Essential for High-Risk Decisions	Zamp Blog	2026-06-19	US	AI & Machine Learning
S2-10	University of Phoenix Research Introduces 16-Stage Human-Centered AI Framework to Optimize Online Student Success	PR Newswire	2026-06-19	US	AI & Machine Learning
S2-11	Deep Learning Framework Improves Doppler Shift Modeling in Radial-Velocity Data Under Stellar Activity Towards Earth-Mass Exoplanet Detection	arXiv (via Astrobiology)	2026-06-19	International	AI & Machine Learning
S2-12	Liquid Cooling Becomes New Standard for AI Data Centers as 100kW+ High-Density Servers Push Air Cooling to Its Limits	MEP Academy	2026-06-12	US	AI & Machine Learning
S2-13	AI Data Center Market to Hit $21-49 Billion by 2026, Power Supply Emerges as Critical Constraint	Digital Applied	2026-06-12	US	AI & Machine Learning
S2-14	arXiv Paper: Looped World Models (LoopWM) Achieve 100x Parameter Efficiency, Resolving Fidelity-Cost Tension in Long-Horizon AI Simulation	arXiv (cs.LG)	2026-06-17	International	AI & Machine Learning

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S2-15	arXiv Preprint 'ThousandWorlds' Introduces New Benchmark for AI Climate Emulation of Potentially Habitable Exoplanets	Astrobiology	2026-06-19	International	AI & Machine Learning
S2-16	NIH-Funded Study: AI Tool 'ApexGo' Accelerates Antibiotic Development, 68% of Optimized Peptides Show Enhanced Efficacy	National Institutes of Health (NIH)	2026-06-17	US	AI & Machine Learning
S2-17	arXiv Paper: Novel Method Distills Latent Electrostatics from Foundation Machine Learning Interatomic Potentials, Enhancing Born Effective Charge and IR Spectra Calculation Efficiency	arXiv (physics.comp-ph)	2026-06-12	International	AI & Machine Learning
S2-18	EU AI Act Implementation Accelerates: Poland Passes AI Systems Act, Ireland to Establish National AI Office	EU Artificial Intelligence Act	2026-06-17	—	AI & Machine Learning
S2-19	Multimodal AI Becomes Frontier Model Standard in 2026: OpenAI GPT-4o Leads with Real-time, Emotionally Aware Processing	explainx.ai	2026-06-16	US	AI & Machine Learning
S2-20	Protegrity Executive Warns: Stronger Governance, Beyond Performance, Crucial for Frontier AI Model Security Amidst White House Executive Order	Protegrity	2026-06-12	US	AI & Machine Learning
S2-21	AI Data Centers Enhance Sustainability, Efficiency with Liquid Cooling Solutions Scaling to Multi-Megawatt Levels	Facilitiesnet	2026-06-16	US	AI & Machine Learning
S2-22	Yutori's Scouts Reports Major AI Startup Funding: TensorWave Secures $350M Series B, Sarvam AI $234M Series B, Poetic $50M, and NewCore $66M Seed Round	Scouts by Yutori	2026-06-15	Japan	AI & Machine Learning
S2-23	EU AI Act Bans Non-Consensual Intimate Imagery AI, Extends High-Risk Deadlines to 2027/2028 for Compliance Planning	RadarFirst	2026-06-19	—	AI & Machine Learning
S2-24	PubMed Review Highlights 'Translational Gap' in AI Drug Discovery, Emphasizing Need for Data Quality, Model Interpretability, and Prospective Clinical Validation	PubMed (via Google Search)	2026-06-19	International	AI & Machine Learning
S2-25	Sanofi Transforms into "First AI-Powered Biopharma at Scale," Integrating AI Across Full Value Chain for Enhanced Manufacturing Yields and Business Insights	IntuitionLabs	2026-06-14	France	AI & Machine Learning
S2-26	Mass General Brigham Develops Multilingual BRIDGE AI Benchmark, Exposing Significant LLM Performance Gaps in Real-World Patient Care Text vs. Standardized Exams	Mass General Brigham	2026-06-17	US	AI & Machine Learning
S2-27	India's Avataar AI Unveils 'Varya' Text-to-Video AI Model with Breakthrough Localized Content Generation, Accelerating Digital Storytelling	The Economic Times	2026-06-15	India	AI & Machine Learning

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S2-28	Liquid Cooling Becomes Imperative for AI Data Centers: Addressing 100kW+ Rack Densities, Enhancing Efficiency, and Supporting Next-Gen Hardware	MEP Academy	2026-06-12	International	AI & Machine Learning
S2-29	NVIDIA Maintains 80% AI Chip Market Dominance via CUDA, But Google TPU, AMD, and Custom Silicon Intensify Competition	WEEX Crypto Wiki	2026-06-12	International	AI & Machine Learning
S2-30	Multimodal AI in 2026: GPT-4o Highlights Real-time Voice with Emotion, Integrating Text, Image, Audio, and Video as Standard for Frontier Models	explainx.ai	2026-06-16	International	AI & Machine Learning
S2-31	Hymalaia Reports: Enterprises Accelerate Autonomous AI Agent Adoption in 2026 Driven by Independent Data Access and Multi-Step Workflow Execution Capabilities	Hymalaia	2026-06-12	International	AI & Machine Learning
S2-32	NVIDIA's Full-Stack AI Infrastructure, from Silicon to Cloud, With CUDA as Its Primary Moat, Explained by Data Science Collective	Data Science Collective - Medium	2026-06-13	US	AI & Machine Learning
S3-01	Quantum Machines Secures Majority Share in Quantum Computing Control Systems Market, Acquires Hungary's PCB Engineering	Quantum Zeitgeist	2026-06-19	US	Quantum Computing
S3-02	KAIST Achieves Tenfold Boost in Atomic Qubit Control Fidelity with Deep Neural Networks	Quantum Zeitgeist	2026-06-19	South Korea	Quantum Computing
S3-03	QuEra Targets 2028 for First Fault-Tolerant Quantum Computer 'Libra' on Amazon Braket, Deepens AWS Alliance	QuEra Computing	2026-06-15	US	Quantum Computing
S3-04	Atom Computing and Phasecraft Partner to Accelerate Materials Discovery, Marking a Toric Code Quantum Error Correction Milestone	AiThority	2026-06-15	US	Quantum Computing
S3-05	Microsoft and Quantinuum Announce 800-Fold Reduction in Quantum Logical Error Rates, Paving Way for Fault-Tolerant Computing	Microsoft Quantum	2026-06-12	US	Quantum Computing
S3-06	National Initiatives Propel Quantum Investment Boom: Global VC Funding Accelerates, Concentrating Half of Post-2025 Deals in Past 18 Months	Preqin	2026-06-16	Global	Quantum Computing
S3-07	Marin Ivezic Warns: Massive PQC Key and Signature Sizes Threaten to Overwhelm Network Infrastructure	Marin Ivezic	2026-06-13	Global	Quantum Computing
S3-08	Alice & Bob Unveils 18-Cat Qubit 'Helium' System for Fault-Tolerant Quantum Research	Alice & Bob	2026-06-18	France	Quantum Computing

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S3-09	PNNL Charts Course for Practical Quantum Advantage, Targeting 100+ Logical Qubits	PNNL (Pacific Northwest National Laboratory)	2026-06-15	US	Quantum Computing
S3-10	Microsoft Unveils 'Majorana 2' Topological Quantum Chip, Targeting 1000x Qubit Reliability and 2029 Commercialization	Marc Pope	2026-06-12	US	Quantum Computing
S3-11	Quantum Leaps in Industrial Optimization: BQP Unveils Hybrid Algorithms and Immediate Value with Quantum-Inspired Solutions	BQP	2026-06-16	Global	Quantum Computing
S3-12	PsiQuantum Breaks Ground on World's First Utility-Scale, Fault-Tolerant Quantum Computing Facility in Australia	PsiQuantum	2026-06-17	Australia	Quantum Computing
S3-13	Illinois Bets Big on Quantum: Over $700 Million Invested, Four National Hubs Position State for Global Leadership	INQUIRE Quantum Innovation Symposium (via Illinois Economic Development Corporation)	2026-06-12	US	Quantum Computing
S3-14	Cleveland Clinic and IBM's Quantum Partnership Pioneers Biomedical Discovery, Simulating Record-Shattering 12,000-Atom Protein	Becker's Hospital Review	2026-06-15	US	Quantum Computing
S3-15	Quantinuum Unveils Helios: A 98-Qubit All-to-All Connected Trapped-Ion Quantum Processor in Nature	PubMed (Nature)	2026-06-18	US	Quantum Computing
S3-16	Quantum-Informed Machine Learning Unveils Mechanism for Practical Advantage in Predicting Chaotic Systems	arXiv	2026-06-12	Global	Quantum Computing
S3-17	D-Wave Demonstrates Million-Fold Quantum Computational Advantage for Materials Discovery	D-Wave Quantum	2026-06-16	Canada	Quantum Computing
S3-18	Atom Computing Secures Over $300M, Including $100M Series C and CHIPS Act LOI, to Scale Neutral Atom Quantum Computers	SuperbCrew, Startup Researcher, Crunchbase News, SiliconANGLE	2026-06-17	US	Quantum Computing
S3-19	Microsoft Expands Azure Quantum Elements with Novel Chemical Workflows to Accelerate Drug Discovery	Microsoft (via Tech Media)	2026-06-12	US	Quantum Computing
S3-20	Atom Computing and Nu Quantum Partner to Accelerate Utility-Scale Quantum Computing via Photonic Networking	Photonics Online	2026-06-18	US	Quantum Computing

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S3-21	D-Wave Quantum Achieves Computational Advantage in Materials Discovery, Solving Million-Year Classical Problem in Minutes	D-Wave Quantum	2026-06-16	Canada	Quantum Computing
S3-22	Protocol-Based Benchmarking Reveals IBM Heron Outperforms Eagle in Quantum Advantage Tasks	arXiv	2026-06-12	Global	Quantum Computing
S3-23	IBM Research Demonstrates Quantum Computing's Role in Optimizing Insurance Portfolios for Allstate	IBM Research blog	2026-06-17	US	Quantum Computing
S3-24	U.S. Government Prepares Major Quantum Investment; Fujitsu & RIKEN Target 10,000+ Physical Qubits by 2031	moomoo Community	2026-06-12	USA, Japan	Quantum Computing
S3-25	Germany Launches CHIRON Project to Build Quantum Communication Network with Entanglement-Based QKD	SQuaD	2026-06-16	Germany	Quantum Computing
S3-26	EU High-Level Board Outlines Strategy for Quantum Tech Leadership, Proposing "Chips Act 2.0"	EU High-Level Board (via `vertexaisearch.cloud.google.com`)	2026-06-19	Europe	Quantum Computing
S3-27	QBN Analysis Highlights New Quantum Geopolitics: U.S. $2B Investment Shifts Towards Sovereign Hardware Control	QBN	2026-06-19	USA, Europe	Quantum Computing
S3-28	RIKEN R-CCS Unveils ROQUO: Japan's New Quantum-HPC Supercomputer Integrates Fugaku with IBM and Quantinuum	R-CCS	2026-06-19	Japan	Quantum Computing
S3-29	U.S. Government Commits $2 Billion to Quantum Industry, Acquiring Stake in GlobalFoundries	Daum	2026-06-13	US	Quantum Computing
S3-30	Amazon Predicts First Commercially Useful Quantum Computers Within 5-7 Years, Intensifying Big Tech Race	BigGo Finance	2026-06-18	US	Quantum Computing
S3-31	U.S. and Japan Forge $1 Billion Strategic Partnership in Quantum and Advanced AI Technologies	SDG News	2026-06-12	USA, Japan	Quantum Computing
S3-32	Japanese Quantum Startup Yaqumo Secures Seed Extension Funding from U.S. VC Alumni Ventures, Marking First Investment in Japan	Yaqumo	2026-06-12	Japan	Quantum Computing
S3-33	UK and Japan Expand Quantum Partnership with Strong Focus on Commercial Deployment	Reddit (r/japannews)	2026-06-16	UK, Japan	Quantum Computing
S3-34	HPE Expands Strategic Partnerships with Intel, Quantinuum, and Others for Hybrid Quantum Supercomputing	Marketscreener	2026-06-15	US	Quantum Computing
S3-35	Pasqal and Thales Partner on Quantum-Enhanced Radar for Defense, Validating Neutral Atom Technology	Quantum Insider News	2026-06-12	France	Quantum Computing

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S3-36	Rigetti Computing's Stock Downturn and High Burn Rate Highlight Quantum Computing Commercialization Challenges	Kavout	2026-06-17	US	Quantum Computing
S3-37	SMBs Face Urgent PQC Migration Deadline by 2030 as NIST Finalizes Quantum-Resistant Standards	Infonaligy (via Google Cloud)	2026-06-12	US	Quantum Computing
S3-38	Evertrust Unveils 24-Month Roadmap for Enterprise PKI Migration to NIST PQC Standards FIPS 203, 204, 205	Evertrust	2026-06-13	Canada	Quantum Computing
S3-39	Academic Paper Analyzes Hybrid PQC-QKD Network Overhead, Proposing Zero-Trust Quantum-Safe Framework	Frontiers in Computer Science	2026-06-15	Switzerland	Quantum Computing
S3-40	Quantinuum and Sandia National Laboratories Announce 98-Qubit Helios Achieves 99.921% Two-Qubit Gate Fidelity in Nature Publication	Quantum Computing Report	2026-06-18	US	Quantum Computing
S3-41	U.S. Department of Commerce Announces $2.013 Billion Quantum Investment Under CHIPS Act; IBM to Establish Quantum Chip Foundry	SRI International | Qubits & Pieces - Medium	2026-06-12	US	Quantum Computing
S3-42	Harsh Realities of PQC Migration: Hybrid Deployment Complexities and Global Adoption Deadlines Revealed	Marin Ivezic	2026-06-13	UK	Quantum Computing
S3-43	Palo Alto Networks Releases NIST PQC Migration Strategies, Standards, and Tips for Proactive Readiness	Palo Alto Networks	2026-06-12	US	Quantum Computing
S3-44	Quantinuum's H2 Processor Achieves 800x Logical Qubit Fidelity with Quantum Error Correction, Published in Nature	TechTonic Times	2026-06-14	UK	Quantum Computing
S3-45	QuEra Computing Announces 'Libra' Fault-Tolerant Quantum Computer to Launch on Amazon Braket in 2028, Expands AWS Collaboration	QuEra Computing (Press Release)	2026-06-15	US	Quantum Computing
S3-46	Microsoft Accelerates Quantum Roadmap: Majorana 2 Chip Achieves 1000x Qubit Lifetime Improvement, Aims for Commercial Quantum Computer by 2029	HTX	2026-06-15	US	Quantum Computing
S3-47	IBM Research Highlights Progress Towards Quantum Advantage by 2026 and Fault-Tolerant Quantum Computing by 2029	IBM Research	2026-06-17	US	Quantum Computing
S3-48	IQM and OpenOcean Report Quantum Computing Enters 'Capability Era,' Citing $8.3 Billion Investment in 2025	Business Wire	2026-06-18	Finland	Quantum Computing
S3-49	Quantum Art Validates Scalable Path to Fault-Tolerant Quantum Computing Using Multi-Qubit Gates with 1% Threshold	Quantum Art (via EQS News)	2026-06-16	Germany	Quantum Computing

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S3-50	Research Team Unveils Breakthrough Measurement-Free, Fault-Tolerant Quantum Error Correction with Autonomous On-the-Fly Error Fixing	Simple Science Deep Dive	2026-06-17	US	Quantum Computing
S3-51	Quantonation Makes First Japan Quantum Investment in Yaqumo, Accelerating Neutral-Atom Hardware R&D;	r/informaq - Reddit	2026-06-14	France	Quantum Computing
S3-52	Atom Computing Accelerates Tens of Thousands of Qubit Neutral-Atom Quantum Computer Development with $100M DOC LOI	New Market Pitch	2026-06-18	US	Quantum Computing
S3-53	Quantum X Labs Launches Integrated Quantum Program Combining CliniQuantum Algorithm and QECC Decoder for Enhanced Fidelity in Clinical Trials	Stock Titan (EQS News)	2026-06-18	US	Quantum Computing
S3-54	Alice & Bob Unveils 'Helium Quantum System,' First On-Premise Quantum System for Research Partners Featuring Cat-Qubit Architecture	Alice & Bob (via EQS News)	2026-06-18	France	Quantum Computing
S3-55	Atom Computing and Nu Quantum Partner to Unlock Utility-Scale Quantum Computing via Photonic Networking	PR Newswire	2026-06-17	US	Quantum Computing
S4-01	Tower Semiconductor and Marvell Exceed 5 Million Coherent PIC Shipments for AI Data Centers, Driving High-Performance Connectivity	PIC Magazine	2026-06-16	US	Photonics & Optical Comms
S4-02	Coherent Breaks Ground on Texas InP Fab with $2 Billion NVIDIA Backing to Bolster AI Optical Tech Supply	AI Weekly	2026-06-16	US	Photonics & Optical Comms
S4-03	Credo Semiconductor Details Near-Package Optics (NPO) Adoption Trends, Addressing Power and Performance Challenges in AI Data Centers	Credo Semiconductor Blog	Date unknown	US	Photonics & Optical Comms
S4-04	PhotonCap Explains Characteristics and Data Center Impact of DSP, LPO, NPO, CPO Optical Interconnect Technologies for the AI Era	PhotonCap	Date unknown	US	Photonics & Optical Comms
S4-05	TechInsights Identifies Silicon Photonics as Backbone for HPC and AI Data Centers, Highlighting New Industry Opportunities	TechInsights Blog	Date unknown	Canada	Photonics & Optical Comms
S4-06	SuperX Debuts 1.6T Optical Modules for AI Data Centers at Interop Tokyo 2026, Setting New High-Speed Connectivity Standards	The Datacenter Engineer	2026-06-16	US	Photonics & Optical Comms
S4-07	Arista Networks Unveils 1.6T Networking Platforms for AI Fabrics, Doubling Data Center Bandwidth	DCNN Magazine	2026-06-16	US	Photonics & Optical Comms

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S4-08	International Research Team Develops Ultrafast, Low-Power Chip-Scale Modulators Using Self-Assembled Plasmonic-Organic Hybrid Nanocavities	National Science Review	2026-06-19	UK	Photonics & Optical Comms
S4-09	Ciena Reports Increased AI-Driven Revenue and Raised Guidance, Maintaining Strong Performance in AI Optical Networking Market	Letsdatascience	2026-06-16	US	Photonics & Optical Comms
S4-10	Keysight Expands Photonic Design Automation Portfolio with System-Level Simulation to Accelerate Optical Communications Development	Keysight Newsroom	2026-06-16	US	Photonics & Optical Comms
S4-11	Marvell Highlights Importance of Plasmonics for Higher Bandwidth Optics in the AI Era	Marvell Blog	Date unknown	US	Photonics & Optical Comms
S4-12	RCR Wireless Deepens Analysis of AI-Optical Convergence, Ciena Seen as Leading in Next-Gen Network Construction	RCR Wireless	2026-06-16	US	Photonics & Optical Comms
S4-13	GF Securities Highlights AI Infrastructure Bottlenecks Shifting from GPUs to Optical Interconnects, Including CPO	Futunn News (GF Securities Report)	Date unknown	China	Photonics & Optical Comms
S4-14	Lintes Accelerates Optical Communication R&D; and Manufacturing for AI Connectivity Expansion, Supporting Next-Gen AI Infrastructure	PR Newswire (Lintes)	2026-06-13	Taiwan	Photonics & Optical Comms
S4-15	Zhaolong Cable Advocates Optimal High-Speed Cabling Selection for Large-Scale AI Clusters Entering 1.6T Interconnect Era	Zhaolong Cable	Date unknown	China	Photonics & Optical Comms
S4-16	Semiconductor Today Reports Advances in Picojoule-Class Optical Interconnects, Revolutionizing Power Efficiency for AI Data Centers	Semiconductor Today	2026-06-16	UK	Photonics & Optical Comms
S4-17	Seeking Alpha Highlights Missing Glass and Light Infrastructure Layer in Quantum Market	Seeking Alpha	2026-06-11	US	Photonics & Optical Comms
S4-18	Goldman Sachs Predicts Next Big Wave of AI Infrastructure Investment to Be Optical Communications (Motley Fool Report)	The Motley Fool	2026-06-16	US	Photonics & Optical Comms
S4-19	Barclays Identifies Top Networking Stocks for $1 Trillion AI Infrastructure Buildout, Optical Communications Companies Gain Attention	Investing.com (Barclays Report)	2026-06-16	US	Photonics & Optical Comms
S4-20	BriefGlance Analyzes AI's Trillion-Dollar Shift, Potential Transition from GPUs to Dawn of Optical Computing	BriefGlance	Date unknown	US	Photonics & Optical Comms
S4-21	NTT's Optical Network Ambitions Face Disruption from Rise of AI and NVIDIA, Experts Note	ketodietapp.com (Expert Time)	Date unknown	US	Photonics & Optical Comms

ID	Title	Source	Date	Region	Sub-Topic
S4-22	Futunn News Reports Fierce Upstream Competition Intensifying in Optical Interconnect Market Driven by AI Demand	Futunn News	Date unknown	China	Photonics & Optical Comms
S4-23	Scintil Photonics CEO Highlights Co-Packaged Optics as Essential for AI Data Centers, Overcoming Copper's Limits	Telborg	2026-06-16	UK	Photonics & Optical Comms

Editor's Note

Navigating the Converging AI & Quantum Frontier

The current technological landscape is defined by an unprecedented convergence of AI, advanced computing, and next-generation infrastructure. The insatiable demand for AI compute is not merely driving chip innovation but fundamentally reshaping the entire IT & Electronics supply chain, from advanced packaging and optical interconnects to data center cooling. Western manufacturers, investors, and executives must recognize that these once-distinct domains are now inextricably linked, with advancements in one directly impacting the others.

Strategic foresight demands a shift from siloed R&D; to integrated ecosystem development. The race for technological sovereignty, evidenced by significant government investments in the US and EU, underscores the critical need for domestic capabilities in advanced packaging, quantum hardware, and secure AI systems. Companies that proactively invest in cross-domain R&D;, secure long-term supply chain partnerships, and adapt to emerging regulatory frameworks (like the EU AI Act and NIST PQC standards) will be best positioned to capitalize on the multi-trillion-dollar opportunities ahead.

The next 12-24 months will be pivotal. Bottlenecks are shifting from raw compute power to the 'picks and shovels' of advanced packaging and optical data transfer. Simultaneously, the foundational work in quantum computing is moving from theoretical breakthroughs to tangible fault-tolerance milestones, while PQC migration becomes an urgent cybersecurity imperative. Western leaders must act decisively to secure critical resources, foster innovation, and build resilient, future-proof technology stacks.

- ◆ How will our current AI strategy adapt to the shifting bottlenecks in advanced packaging and optical interconnects by Q4 2026?
- ◆ What specific investments are required to ensure our supply chain is resilient against geopolitical shifts and compliant with emerging AI/PQC regulations by 2028?
- ◆ What cross-functional teams can we establish this week to integrate insights from advanced packaging, AI, quantum, and photonics into our 2027 product roadmap?

Troy Technical Weekly Editorial Board Chief Technology Strategist

Next Issue Vol. 49 Monday, June 29, 2026 06:00 JST Feature: Edge AI & Industrial IoT

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